

ABSTRACT OF THE DISCLOSURE

MULTICHIP MODULE HAVING CHIPS ON TWO SIDES

A multichip module including a frame having contacts suitable for making an electrical connection with an article, preferably a printed wiring board or similar, which is the next level of packaging, a multilayer thin film structure mounted to the frame, and semiconductor devices mounted to the thin film structure with at least one semiconductor device on each of two opposed sides of the thin film structure. The thin film structure includes arrays of pads on opposed surfaces of the thin film structure for connecting the thin film structure to the semiconductor devices and the frame. The thin film structure further includes wiring for chip to chip connectivity and for connecting to the frame.